

What is claimed is:

- 1 1. A cleaning device comprising:
 - 2 a pure water supply;
 - 3 first and second injectors that eject pure water supplied from the pure water supply onto a
 - 4 wafer;
 - 5 first and second nozzles attached to ends of the respective first and second injectors;
 - 6 a brush that cleans the wafer during horizontal movement between a center and edges of
 - 7 the wafer; and
 - 8 a brush arm that supports and moves the brush,
 - 9 wherein the first injector ejects the pure water at an upper position of the wafer toward
 - 10 the center of the wafer, and
 - 11 wherein the second injector is disposed adjacent to the brush along one side of the brush
 - 12 arm, and supplies the pure water toward the wafer.
- 1 2. The cleaning device as recited in claim 1, wherein the second nozzle is disposed such
- 2 that it faces a top surface of the wafer that is in contact with the brush.
- 1 3. The cleaning device as recited in claim 1, wherein the first injector is arranged to be
- 2 perpendicular to the second injector.
- 1 4. The cleaning device as recited in claim 3, wherein the brush arm moves in a direction
- 2 parallel to linear orientation of the first injector.

5. The cleaning device as recited in claim 1, wherein the brush arm is moved vertically to keep the brush a desired distance from a surface of the wafer.

6. The cleaning device as recited in claim 1, wherein the brush arm is moved vertically to keep the brush in contact with a surface of the wafer.

7. The cleaning device as recited in claim 1, wherein the brush moves horizontally with respect to the direction of the first injector.

8. A cleaning device comprising:
 - a pure water supply;
 - first injector that ejects pure water supplied from the pure water supply onto a central portion of the wafer;
 - a plurality of second injectors that eject pure water supplied from the pure water supply onto the wafer;
 - a first nozzle attached to the first injector;
 - a plurality of second nozzles respectively attached to the second injectors;
 - a brush that cleans the wafer during horizontal movement between a center and edges of the wafer, while the pure water is ejected by the first and second nozzles; and
 - a brush arm that supports and moves the brush,

13 circumference of the brush arm, the end of the pipelines facing a top surface of the wafer.

1 9. The cleaning device as recited in claim 8, wherein the plurality of second injectors are
2 tightly fixed to the brush arm by a fixing apparatus.

1 10. The cleaning device as recited in claim 8, wherein the first injector is arranged to be
2 perpendicular to the plurality of second injectors.

1 11. The cleaning device as recited in claim 10, wherein the brush arm moves in a
2 direction parallel to a linear orientation of the first injector.

1 12. The cleaning device as recited in claim 8, wherein the brush arm is moved vertically
2 to keep the brush a desired distance from a surface of the wafer.

1 13. The cleaning device as recited in claim 8, wherein the brush arm is moved vertically
2 to keep the brush in contact with a surface of the wafer.